

N32H785EC

Product Brief

The N32H785xxx7EC series adopts a high-performance dual-core architecture. The ARM Cortex-M7 core is the main core, running at frequencies up to 600MHz, supporting double-precision floating-point operations and DSP instructions. The Cortex-M4 core is the auxiliary core, running at frequencies up to 300MHz. It has (2/4MB) of onchip FLASH, integrates up to 1504KB of SRAM (including 1024KB TCM SRAM and 480KB SRAM) + 4KB Backup SRAM, integrates 3 12-bit 5Msps ADCs, 4 high-speed comparators, 6 12-bit DACs, and features multiple high-speed communication interfaces including U(S)ART, I2C, xSPI, SPI, USBFS Dual Role, USBHS Dual Role, CAN-FD, SDRAM, FEMC, SDMMC, 10/100/1000M Ethernet, and EtherCAT. It supports digital camera interface (DVP), TFT-LCD graphic interface, JPEG hardware encoder/decoder and GPU. The chip has a built-in high-performance encryption algorithm hardware acceleration engine supporting AES/TDES, and SHA algorithms, supports TRNG true random number generator, and supports CRC8/16/32. It supports up to 166 GPIOs and is available in TFBGA240+25 package.

Key Features

- Dual-Core Architecture CPU (Cortex-M7 and Cortex-M4F)
 - ARM Coretex-M7
 - o 32-bit ARM Cortex-M7 core, double-precision floating-point unit, supports DSP instructions and MPU
 - Built-in 32KB instruction cache and 32KB data cache with ECC
 - o Maximum frequency 600MHz, 1284 DMIPS
 - ARM Coretex-M4F
 - 32-bit ARM Cortex-M4F core + FPU, single-cycle hardware multiply-divide instructions, supports DSP instructions and MPU
 - Built-in 16KB instruction cache and 16KB data cache with parity checking, supports Flash acceleration unit with 0 wait state program execution
 - Maximum frequency 300MHz, 375 DMIPS

Encrypted Memory

- 2M/4M Byte on-chip Flash, supports encrypted storage with automatic program decryption during execution
- 1504KB built-in SRAM with ECC support
 - o 1024KB TCM SRAM, configurable as D-TCM, I-TCM or SRAM
 - o 480KB on-chip SRAM
- 4KB Backup SRAM with ECC support

Operating Modes

- Run mode
- SLEEP mode: AXI enabled, AHB enabled
- Stop0 mode: SRAM, TCM, RTC, LSE, IWDG enabled
- Stop2 mode: Flash in standby mode, SRAM, TCM, RTC, LSE, IWDG, Backup SRAM, backup registers enabled,
 I/O state maintained



- Standby mode: Backup SRAM, RTC, IWDG, LSE, backup registers enabled, SRAM and TCM disabled
- VBAT mode: Backup SRAM, RTC, LSE, backup registers enabled

Clock

- 4MHz~48MHz external high-speed crystal
- 4MHz~50MHz external clock input
- 32.768KHz external low-speed crystal
- Three built-in high-speed PLLs
- Built-in MSI clock supporting 31.25K/62.5K/125K/250K/500K/1M/2M/4M/8M/16MHz configurations
- Internal high-speed RC 64MHz
- Internal low-speed RC 32KHz

Reset

- Supports power-on/power-down/external pin reset
- Supports watchdog reset and software system reset
- Supports programmable voltage detection

• High-Speed Communication Interfaces

- 8 USART interfaces/7 UART interfaces, supporting ISO7816, IrDA, LIN
- 2 LPUART interfaces
- 7 SPI interfaces, supporting master/slave modes, up to 50 MHz
- 10 I2C interfaces, up to 3.4 MHz, configurable master/slave modes, supports dual address response in slave mode
- 1 USBFS Dual Role interface
- 1 USBHS Dual Role interface with built-in high-speed PHY
- 8 CAN-FD bus interfaces
- 2 Ethernet MAC interfaces: ETH1 supports 10M/100M/1000M rates, ETH2 supports 10M/100M rates, both support IEEE 1588 time synchronization protocol
- 1 EtherCAT slave interface (ESC), up to 100Mbit/s, supports 2 MII ports, 8 fieldbus memory management units (FMMU), 8 synchronization managers (SM), 64-bit distributed clock (DC)

• High-Performance Analog Interfaces

- 3 12-bit 5Msps ADCs, supporting 12-bit/10-bit resolution with hardware oversampling up to 16-bit, up to 55 external single-ended input channels, 5 internal single-ended input channels, supporting single-ended and differential modes
- 4 high-speed analog comparators
- 6 12-bit DACs: 2 1Msps DACs supporting buffered/unbuffered external output (internal output only supports unbuffered mode; simultaneous internal/external output requires buffer enabled), 4 DACs supporting only internal chip output with 15Msps sampling rate and unbuffered output
- 2 MCO outputs, configurable to output SYSCLK, HSE, MSI, LSE, LSI, HSI64 or PLL clock division
- 1 reference voltage VREFBUF (configurable: 1.5V/1.8V/2.048V/2.5V)
- 1 temperature sensor

Audio Interfaces

4 I2S interfaces, supporting half/full duplex modes, audio sampling rates from 8KHz to 192KHz



8 PDM digital microphone interfaces built into DSMU

Memory Expansion Interfaces

- 1 FEMC (Flexible External Memory Controller) interface, 100 MHz bus rate, SRAM/PSRAM/Nor Flash supporting 16/32-bit data width, NAND Flash supporting 8/16-bit data width
- 1 xSPI interface, supporting 1/2/4/8-bit data width, master/slave configurable, up to 133 MHz, usable for expanding SRAM,
 PSRAM and Flash, supports XIP
- 1 SDRAM interface, up to 133 MHz
- 2 SDMMC interfaces, supporting SD/SDIO 3.0, eMMC 4.51 format, up to 104MHz

• Image Processing Interfaces

- 2 digital camera interfaces (DVP), supporting 8/10/12/16bit, up to 110MHz
- 1 TFT-LCD display interface, supporting up to 24-bit parallel digital RGB LCD with all signal interfaces for direct connection to various LCD and TFT panels, resolution up to 1920x1080
- Built-in 2.5D graphics processor supporting image scaling, rotation, mixing, anti-aliasing, texture mapping, etc.
- Hardware JPEG encoder/decoder
- Maximum support for 166 GPIOs, low-speed GPIOs support 5V tolerance (under VDD=3.3V±10% condition)
- Motor control Cordic accelerator, supporting trigonometric and hyperbolic functions, supports floating-point input and output
- Delta Sigma Module Unit (DSMU)
- Built-in filter algorithm accelerator FMAC, supporting FIR and IIR filtering
- 3 high-speed DMA controllers, each supporting 8 channels, 1 MDMA supporting 16 channels, fully configurable channel source and destination addresses
- RTC real-time clock, supporting perpetual calendar with leap year, alarm events, periodic wake-up, internal/external clock calibration

Timers

- 2 16-bit ultra-high precision timers (SHRTIM1/SHRTIM2), highest control precision 100ps, each with 1 master timer and 6 16-bit slave timer units. Each timer unit has 2 independent channels, supporting 12 independent PWM outputs or 6 pairs of complementary PWM outputs
- 4 16-bit advanced timers, supporting input capture, complementary output, quadrature encoder input, etc., highest control
 precision 3.3ns; each timer has 6 independent channels, 4 of which support 4 pairs of complementary PWM outputs
- 10 16-bit general-purpose timers (GTIMA17/GTIMB13), each with 4 independent channels, supporting input capture, output compare, PWM generation
- 4 32-bit basic timers (BTIM1~4)
- 5 16-bit low-power timers (LPTIM1~5), operational in Stop2 mode
- 2x 24-bit SysTick, 2x 14-bit window watchdogs (WWDG), 2x 12-bit independent watchdogs (IWDG)

Programming

- Supports SWD/JTAG online debugging interfaces
- Supports USB, UART Bootloader

Security Features

FLASH has up to 4 encryption partitions, supporting storage encryption





- Supports write protection (WRP), multiple read protection (RDP) levels (L0/L1/L2)
- Built-in cryptographic hardware acceleration engine, supporting AES/TDES, SHA, SM4 algorithms
- TRNG true random number generator, CRC8/16/32 computation
- Supports secure boot, encrypted program download, secure update, external high and low-speed clock failure detection
- Supports tamper detection

• 128-bit UCID supported in OTP

Operating Conditions

- Operating voltage range: 2.3V~3.6V
- Chip junction temperature range: -40°C~125°C

Certification

- USB IF
- IEC61508 SIL2

Package

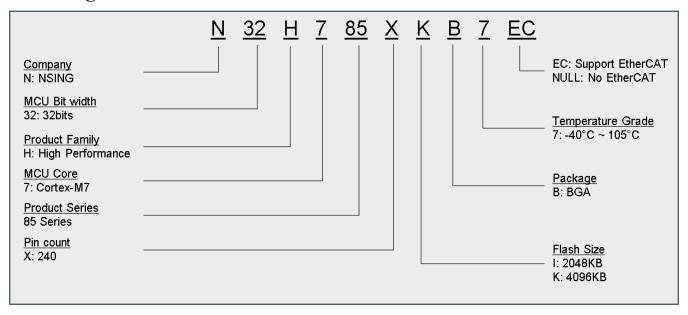
- TFBGA240+25 (14mm x 14mm)

Ordering Model

Series	Model
N32H785xxx7EC	N32H785XKB7EC, N32H785XIB7EC



1 Naming Convention





2 Product Mode and Resources Configuration

Table 0-1 N32H785xxx7ECSeries Resource Configuration

Devi	ice Model	N32H785XKB7EC	N32H785XIB7EC								
Flasl	h (KB)	4096	2048								
	TCM	1024									
SRAM (KB)	System RAM	480									
(RD)	Backup RAM	4									
C	M7	600M	ИНZ								
Core	M4	300MHz									
Operat	ing Voltage	2.3V~	3.6V								
DCDC ((step-down)	Yes									
	Cordic	Yes									
Coprocessor	DSMU	Yes									
<u> </u>	FMAC	Yes									
	SHRTIM	2									
	ADTIM	4									
•	GPTIM	10									
•	BSTIM	4									
Timers	LPTIM	5									
•	SysTick timer	2									
•	WWDG	2*14bit									
•	IWDG	2*12bit									
•	RTC	Yes									
	SPI/I2S	7/4									
•	I2C	10									
	USART	8									
	UART	7									
•	LPUART	2									
Communica	USBHS Dual Role	1									
tion Interfce	USBFS Dual Role	1									
<u> </u>	CAN FD	8									
-	ESC	Yes									
	10/100M ETH	1									
	10/100/1000M ETH	1									
Expanded Storage	SDRAM	Ye	s								
	xSPI	1									
	FEMC	Yes									
	SDMMC	2									
	12bit ADC	3									
Analog	12bit DAC Number of channels	2+4 ⁽¹⁾ 2 External channels									
-	比较器	4									



	VREFBUF	Yes						
	LCDC	Yes						
T	GPU	Yes						
Imaging	JPEG	Yes						
	DVP	2						
	GPIO	166						
	DMA	3						
Numbe	er of channels	24Channel						
1	MDMA	1						
Numbe	er of channels	16Channel						
Algori	thm Support	DES/3DES, AES, SHA1/SHA224/SHA256, CRC8/16/CRC32						
Security Protection		Read/write protection (RDP/WRP), storage encryption, secure boot						
Package		TFBGA240+25						

Note: 4 DACs only support internal connection and cannot output to GPIO





3 Package

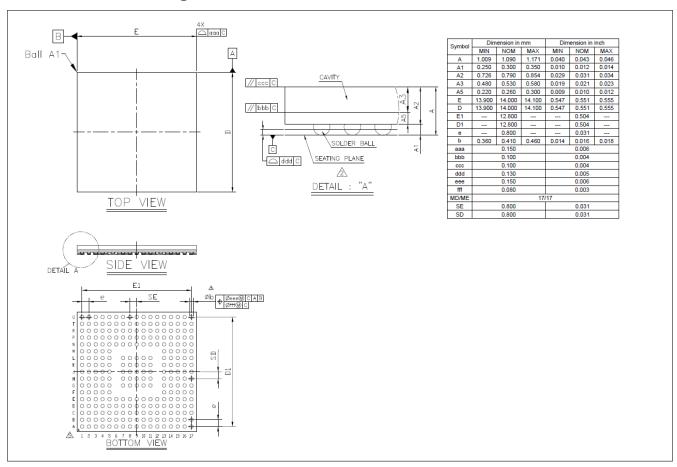
TFBGA240+25 Package

TFBGA240+25 Pin Distribution

	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17
A	VSS	PI6	PI5	PI4	PB5	NC	VCAP	PK5	PG10	PG9	PD5	PD4	PC10	PA15	PII	PIO	vss
В	$\begin{pmatrix} VBA \\ T \end{pmatrix}$	VSS	PI7	PEI	PB6	VSS	PB4	PK4	PG11	PJ15	\bigcirc PD6	PD3	PC11	PA14	PI2	PH15	PH14
С	OSC3 2_OU T	PC14- OSC3 2_IN	PE2	PE0	PB7	PB3	PK6	PK3	PG12	VSS	PD7	PC12	VSS	PI3	PA13	VSS	NC
D	PE5	PE4	PE3	PB9	PB8	PG15	PK7	PG14	PG13	PJ14	(PJ12)	PD2	PD0	PA10	PA9	PH13	VCAP
Е	(VLXS MPS	PI9	PC13	PI8	PE6	VDD	NC	BOO T0	VDD	(PJ13)	VDD	PDI	PC8	PC9	PA8	USB1 _DP	USB1 DM
F	(VDD SMPS)	VSSS MPS	PI10	PII1	VDD								PC7	PC6	PG8	PG7	(VDD3 3_US B
G	PF2	VFBS MPS	PF1	PFO			VSS	VSS	VSS	VSS	VSS		VDD	PG5	PG6	VSS	NC
Н	PI12	PI13	PI14	PF3	(VDD)		VSS	VSS	VSS	VSS	VSS			PG4	PG3	PG2	PK2
J	OSC_OUT	OSC_IN	VSS	PF5	PF4		VSS	$\sqrt{v_{\rm SS}}$	VSS	VSS	VSS		VDD	PK0	PK1	VSS	vss
K	NRST	PF6	PF7	PF8			VSS	(vss)	VSS	VSS	VSS		$\boxed{\text{VDD}}$	PJI1	VSS	NC	NC
L	$\begin{pmatrix} VDD\\A \end{pmatrix}$	PC0	(PF10)	PF9	VDD		VSS	(vss)	VSS	VSS	VSS		$\boxed{\text{VDD}}$	PJ10	VSS	NC	NC
M	VREF +	PCI	PC2	PC3									$\boxed{\text{VDD}}$	PJ9	VSS	NC	NC
N	VREF -	PH2	PA2	PAI	PA0	PJO	$\boxed{\text{VDD}}$	$\sqrt{\text{VDD}}$	PE10	$\boxed{\text{VDD}}$	VDD	VDD	PJ8	РЈ7	PJ6	VSS	NC
P	VSSA	PH3	PH4	PH5	PI15	PJI	PF13	PF14	PE9	PE11	(PB10)	(PBII)	PH10	PH11	PD15	PD14	VDD
R	PC2_C	PC3_C	PA6	VSS	PA7	PB2	PF12	VSS	PF15	PE12	PE15	PJ5	PH9	PH12	PDII	PD12	PD13
T	PAO_C	$\begin{pmatrix} PA1_{-} \\ C \end{pmatrix}$	PA5	PC4	PBI		(PF11)		PE8	PE13	PH6	VSS	PH8	PB12	PB15	$\boxed{\text{PD10}}$	PD9
U	VSS	PA3	PA4	PC5	PB0	PJ3	PJ4	PGI	PE7	PE14	VCAP	NC	PH7	PB13	PB14	PD8	vss



TFBGA240+25 Package Size







4 Version History

Version	Date	Changes
V1.0.0	2025.4.23	First release





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